
Hybrid Microelectronics Handbook

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Contents

List of Contributors	xi
Preface	xiii

Chapter 1. Introduction to Hybrid Microelectronics	1-1
1.1 Interconnection Substrates	1-2
1.2 Thick Film Technology	1-2
1.3 Thin Film Technology	1-7
1.4 Cofired Ceramic and Glass–Ceramic Technology	1-11
1.5 Printed Wiring Board Technology	1-12
1.6 Laser Trimming	1-15
1.7 Assembly	1-16
1.8 Packaging	1-20
1.9 Advantages of Hybrid Microelectronics	1-20
1.10 Applications and Examples	1-20
1.11 Summary	1-28
Chapter 2. Ceramic Substrates for Hybrid Applications	2-1
2.1 Introduction	2-1
2.2 Basic Properties of Hybrid Substrate Materials	2-2
2.3 Ceramic Compositions for Thick Film Circuits	2-17
2.4 Ceramic Substrate Manufacturing Methods	2-20
2.5 Substrate Cleaning	2-25
2.6 Postfire Processing	2-26
2.7 Substrate Sources and Costs	2-33
References	2-34
Chapter 3. Thick Film Materials and Processes	3-1
3.1 Introduction	3-1
3.2 Thick Film Conductors	3-1
3.3 Thick Film Dielectrics	3-38
3.4 Resistor Materials and Processing	3-69
3.5 Rheology and the Screen Printing Process	3-103
3.6 Quality Control and Manufacturing Processes	3-137

3.7 Nonhybrid Applications	3-141
References	3-143
Chapter 4. Thin Film Materials and Processing	4-1
4.1 Introduction	4-1
4.2 Thin Film Deposition Techniques	4-1
4.3 Substrate Materials	4-8
4.4 Conductor Materials	4-10
4.5 Resistor Materials	4-11
4.6 Capacitor Materials	4-15
4.7 Inductor Materials	4-18
4.8 Emerging Thin Film Materials	4-18
4.9 Thin Film Design Guidelines	4-23
4.10 Fabrication Sequence for Thin Film Resistor-Conductor Circuits	4-31
4.11 Characterization of Thin Films	4-34
4.12 Emerging Technology: Multichip Module Deposited (MCM-D)	4-37
4.13 Conclusion	4-41
Appendix A Deposition Techniques	4-42
Appendix B Metal Etchants for Thin Film	4-53
References	4-53
Chapter 5. Pure Copper Metallization Technologies	5-1
5.1 Introduction	5-1
5.2 Substrates	5-4
5.3 Direct Bond Copper Technology	5-7
5.4 Plated-Copper Technology	5-17
5.5 Active Metal Brazing Copper Technology	5-21
5.6 Comparisons	5-27
5.7 Assembly	5-30
5.8 Thermal Performance	5-36
5.9 Electrical Performance	5-39
5.10 Reliability	5-41
5.11 Applications	5-48
References	5-52
Chapter 6. Assembly of Hybrid Microcircuits	6-1
6.1 Introduction	6-1
6.2 The Decision Support System	6-5
6.3 The Solder Joint	6-10
6.4 Hybrid Assembly Using the Surface Mount Technology	6-17
6.5 Cleaning	6-29
6.6 Repair and Rework	6-41
6.7 Component Attachment	6-46
6.8 Intermetallic Formation	6-52
6.9 Wire Bonding	6-62
6.10 TAB and Flip-Chip Bonding	6-73
6.11 Statistical Process Control	6-80
6.12 Factory Automation	6-90
Bibliography	6-99

Chapter 7. Electronic Packaging of Hybrid Circuits	7-1
7.1 Introduction	7-1
7.2 Requirements of Electronic Packaging	7-2
7.3 Types of Electronic Packages	7-7
7.4 Material Considerations for Electronic Packaging	7-15
7.5 Electronic Package Fabrication	7-19
7.6 Package Sealing	7-23
7.7 Evaluation of Electronic Packages	7-26
7.8 Applications	7-42
7.9 Conclusion	7-43
References	7-44
Chapter 8. Discrete Passive Components for Hybrid Circuits	8-1
8.1 Introduction	8-1
8.2 Capacitors	8-1
8.3 Inductors and Transformers	8-25
8.4 Resistors	8-32
Chapter 9. Cleanrooms for Hybrid Manufacturing	9-1
9.1 Introduction	9-1
9.2 Cleanroom Design	9-4
9.3 Layout Considerations	9-27
9.4 Cleanroom Management	9-44
References	9-60
Chapter 10. Failure Analysis of Hybrid Microelectronics	10-1
10.1 Introduction	10-1
10.2 Who Should Perform a Failure Analysis?	10-3
10.3 What You Should Expect to Get Out of a Failure Analysis	10-5
10.4 Why Hybrid Circuit Failure Analysis is Different from Other Microelectronic Failure Analysis	10-5
10.5 Analytical Approach to Failure Analysis	10-10
10.6 Failure Analysis Documentation and Reports	10-17
10.7 Failure Analysis Tools	10-18
10.8 Typical Hybrid Failure Modes	10-35
10.9 Typical Failure Analysis Examples	10-36
10.10 Failure Analysis in the Future	10-43
10.11 Summary	10-45
Appendix 10.1 Sample: Basic Failure Analysis Report	10-46
Appendix 10.2 Sources of Additional Reading on Failure Analysis	10-53
Chapter 11. Design Methods for Hybrid Circuits	11-1
11.1 Introduction	11-1
11.2 The Design Process	11-2
11.3 The Design Sequence	11-3
11.4 Design of Thick Film Resistors	11-11
11.5 Design of Thin Film Resistors	11-20
11.6 Electrical Considerations in Hybrid Design	11-25

11.7 Thermal Considerations	11-32
11.8 Determination of Conductor Width	11-59
11.9 Determination of Wirebond Size	11-63
11.10 Selection of Substrate Technology	11-64
11.11 Design Guidelines	11-67
11.12 Assembly Materials and Process Selection	11-72
11.13 Reliability Considerations	11-74
11.14 Summary	11-103
References	11-103

Index	1
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